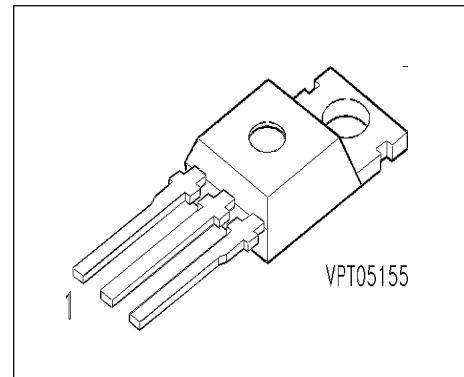


SIPMOS® Power Transistor

- N channel
- Enhancement mode
- Avalanche-rated
- dv/dt rated
- Low on-resistance
- 175°C operating temperature
- also in TO-220 SMD available



Pin 1	Pin 2	Pin 3
G	D	S

Type	V_{DS}	I_D	$R_{DS(on)}$	Package	Ordering Code
BUZ 101	50 V	29 A	0.06 Ω	TO-220 AB	C67078-S1350-A2

Maximum Ratings

Parameter	Symbol	Values	Unit
Continuous drain current $T_C = 31^\circ\text{C}$	I_D	29	A
Pulsed drain current $T_C = 25^\circ\text{C}$	$I_{D\text{puls}}$	116	
Avalanche energy, single pulse $I_D = 29 \text{ A}, V_{DD} = 25 \text{ V}, R_{GS} = 25 \Omega$ $L = 83 \mu\text{H}, T_j = 25^\circ\text{C}$	E_{AS}	70	mJ
Reverse diode dv/dt $I_S = 29 \text{ A}, V_{DS} = 40 \text{ V}, dI_F/dt = 200 \text{ A}/\mu\text{s}$ $T_{j\text{max}} = 175^\circ\text{C}$	dv/dt	6	kV/μs
Gate source voltage	V_{GS}	± 20	V
Power dissipation $T_C = 25^\circ\text{C}$	P_{tot}	100	W
Operating temperature	T_j	-55 ... + 175	°C
Storage temperature	T_{stg}	-55 ... + 175	
Thermal resistance, chip case	R_{thJC}	≤ 1.5	K/W
Thermal resistance, chip to ambient	R_{thJA}	≤ 75	
DIN humidity category, DIN 40 040		E	
IEC climatic category, DIN IEC 68-1		55 / 175 / 56	

Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Static Characteristics

Drain- source breakdown voltage $V_{GS} = 0 \text{ V}, I_D = 0.25 \text{ mA}, T_j = -40^\circ\text{C}$	$V_{(\text{BR})\text{DSS}}$	50	-	-	V
Gate threshold voltage $V_{GS}=V_{DS}, I_D = 1 \text{ mA}$	$V_{GS(\text{th})}$	2.1	3	4	
Zero gate voltage drain current $V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 25^\circ\text{C}$ $V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, T_j = -40^\circ\text{C}$ $V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 150^\circ\text{C}$	I_{DSS}	- - -	0.1 1 10	1 100 100	μA nA μA
Gate-source leakage current $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$	I_{GSS}	-	10	100	nA
Drain-Source on-resistance $V_{GS} = 10 \text{ V}, I_D = 21 \text{ A}$	$R_{DS(\text{on})}$	-	0.036	0.06	Ω

Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Dynamic Characteristics

Transconductance $V_{DS} \geq 2 * I_D * R_{DS(on)max}$, $I_D = 21 \text{ A}$	g_{fs}	7	13.5	-	S
Input capacitance $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$	C_{iss}	-	680	900	pF
Output capacitance $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$	C_{oss}	-	240	360	
Reverse transfer capacitance $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$	C_{rss}	-	90	135	
Turn-on delay time $V_{DD} = 30 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 3 \text{ A}$ $R_{GS} = 50 \Omega$	$t_{d(on)}$	-	15	23	ns
Rise time $V_{DD} = 30 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 3 \text{ A}$ $R_{GS} = 50 \Omega$	t_r	-	55	85	
Turn-off delay time $V_{DD} = 30 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 3 \text{ A}$ $R_{GS} = 50 \Omega$	$t_{d(off)}$	-	100	135	
Fall time $V_{DD} = 30 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 3 \text{ A}$ $R_{GS} = 50 \Omega$	t_f	-	70	95	

Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

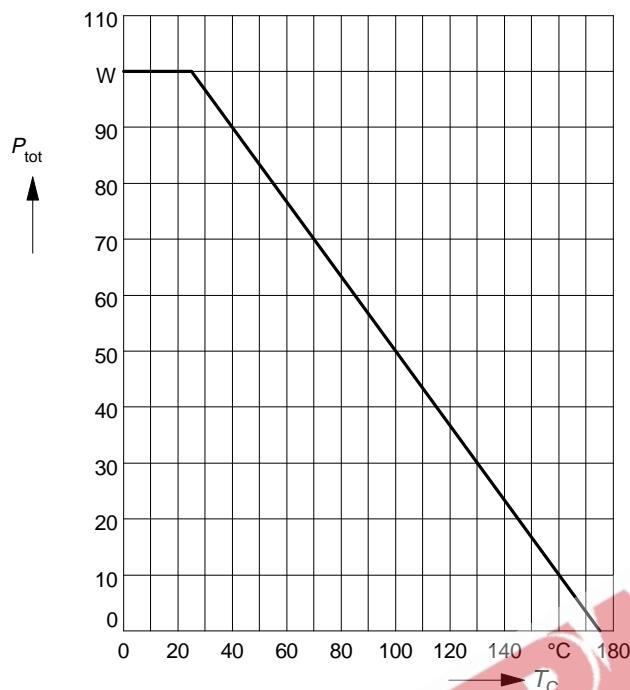
Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Reverse Diode

Inverse diode continuous forward current $T_C = 25^\circ\text{C}$	I_S	-	-	29	A
Inverse diode direct current,pulsed $T_C = 25^\circ\text{C}$	I_{SM}	-	-	116	
Inverse diode forward voltage $V_{GS} = 0\text{ V}, I_F = 58\text{ A}$	V_{SD}	-	1.2	2	V
Reverse recovery time $V_R = 30\text{ V}, I_F=I_S, dI_F/dt = 100\text{ A}/\mu\text{s}$	t_{rr}	-	60	-	ns
Reverse recovery charge $V_R = 30\text{ V}, I_F=I_S, dI_F/dt = 100\text{ A}/\mu\text{s}$	Q_{rr}	-	0.12	-	μC

Power dissipation

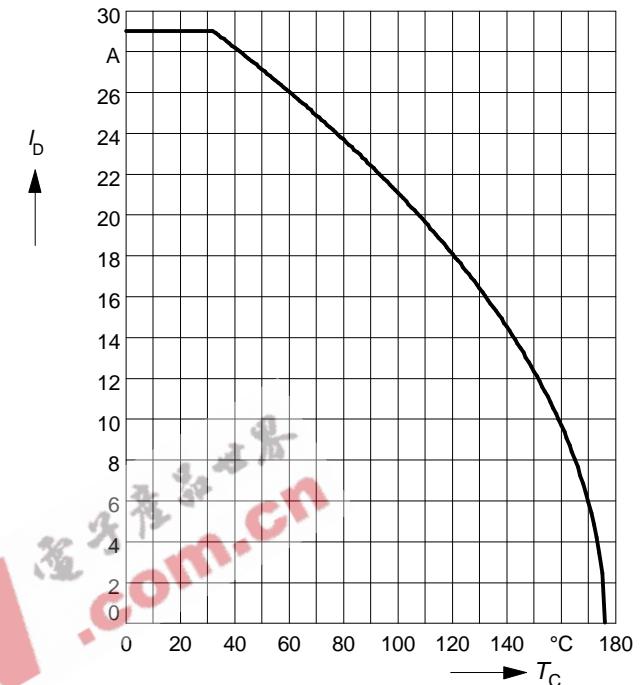
$$P_{\text{tot}} = f(T_C)$$



Drain current

$$I_D = f(T_C)$$

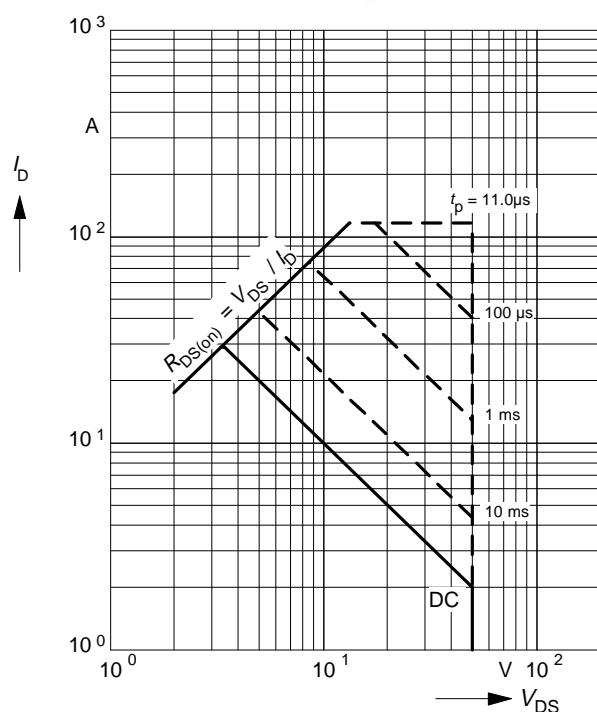
parameter: $V_{GS} \geq 10$ V



Safe operating area

$$I_D = f(V_{DS})$$

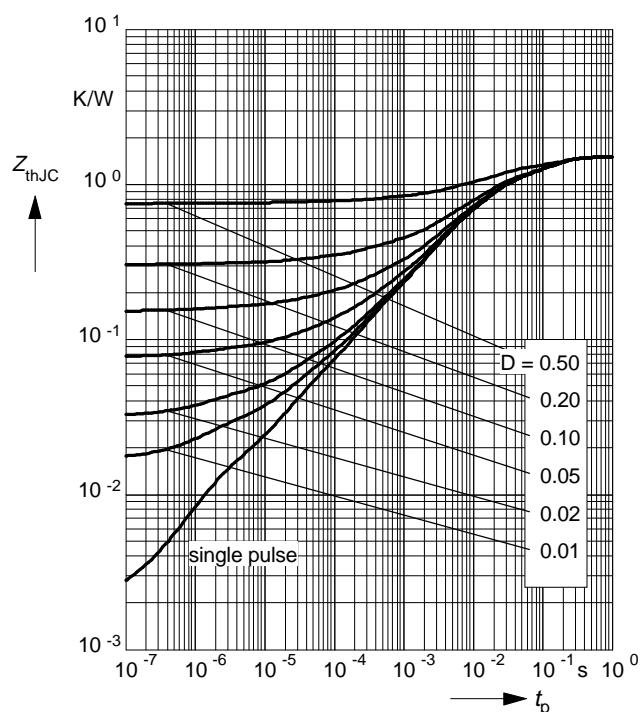
parameter: $D = 0.01$, $T_C = 25^\circ\text{C}$



Transient thermal impedance

$$Z_{\text{thJC}} = f(t_p)$$

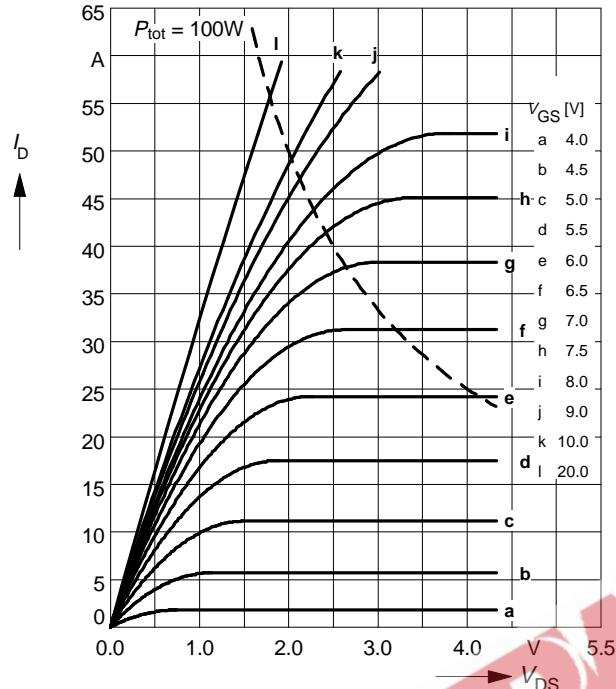
parameter: $D = t_p / T$



Typ. output characteristics

$$I_D = f(V_{DS})$$

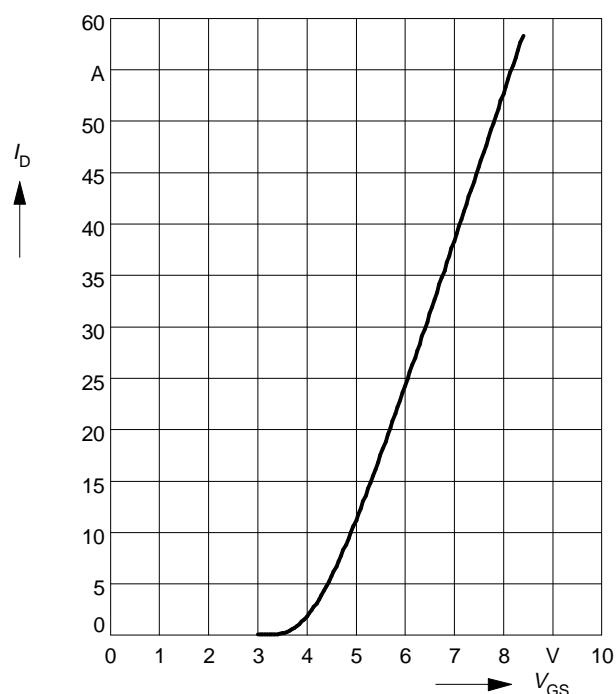
parameter: $t_p = 80 \mu s$



Typ. transfer characteristics $I_D = f(V_{GS})$

parameter: $t_p = 80 \mu s$

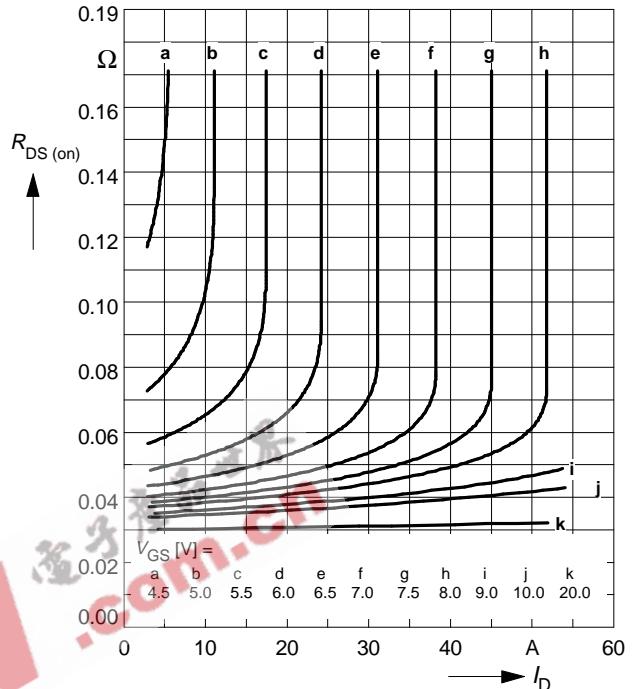
$$V_{DS} \geq 2 \times I_D \times R_{DS(on)} \text{max}$$



Typ. drain-source on-resistance

$$R_{DS(on)} = f(I_D)$$

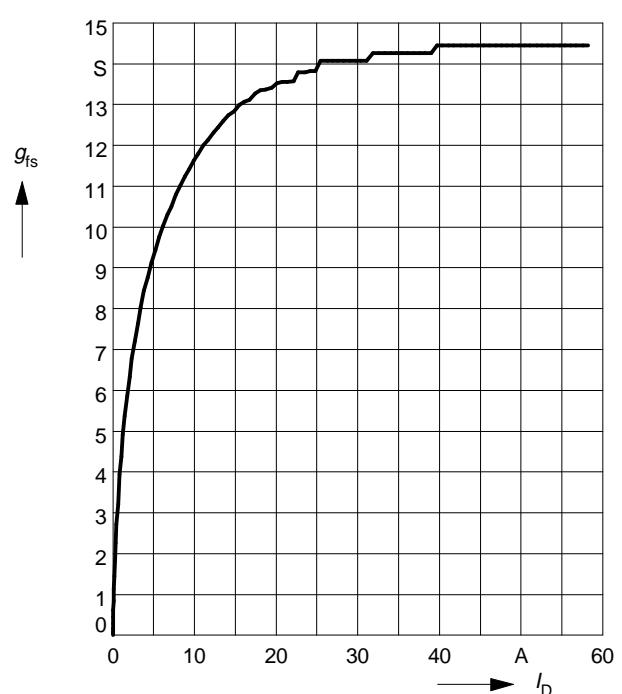
parameter: V_{GS}



Typ. forward transconductance $g_{fs} = f(I_D)$

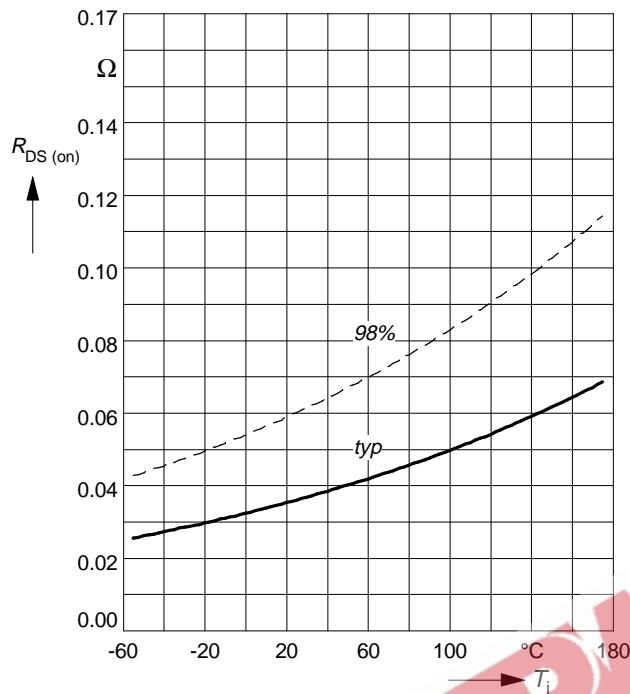
parameter: $t_p = 80 \mu s$,

$$V_{DS} \geq 2 \times I_D \times R_{DS(on)} \text{max}$$



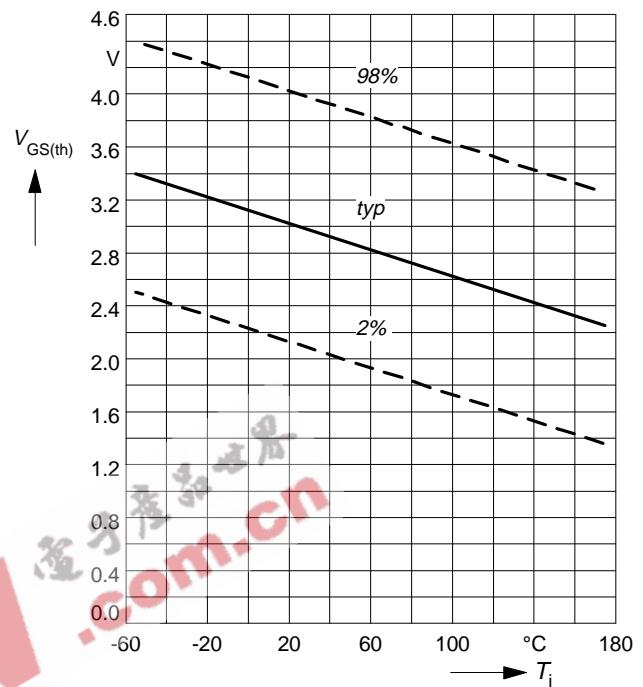
Drain-source on-resistance

$R_{DS(on)} = f(T_j)$
parameter: $I_D = 21 \text{ A}$, $V_{GS} = 10 \text{ V}$



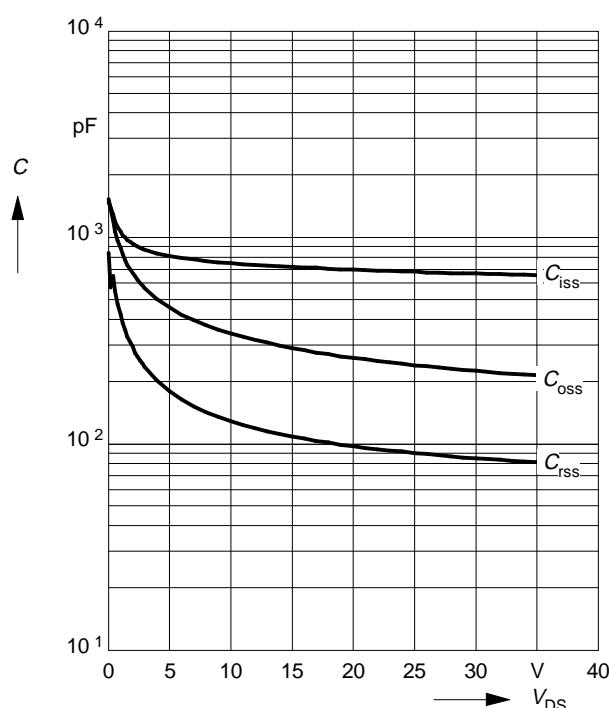
Gate threshold voltage

$V_{GS(th)} = f(T_j)$
parameter: $V_{GS} = V_{DS}$, $I_D = 1 \text{ mA}$



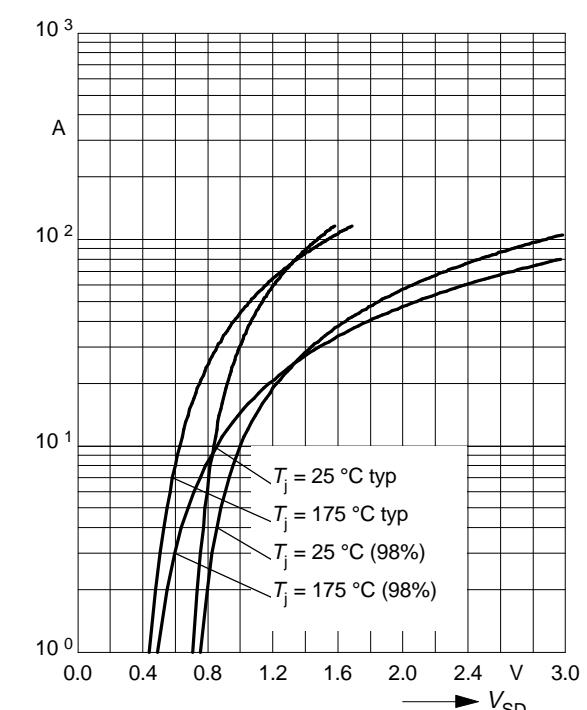
Typ. capacitances

$C = f(V_{DS})$
parameter: $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$

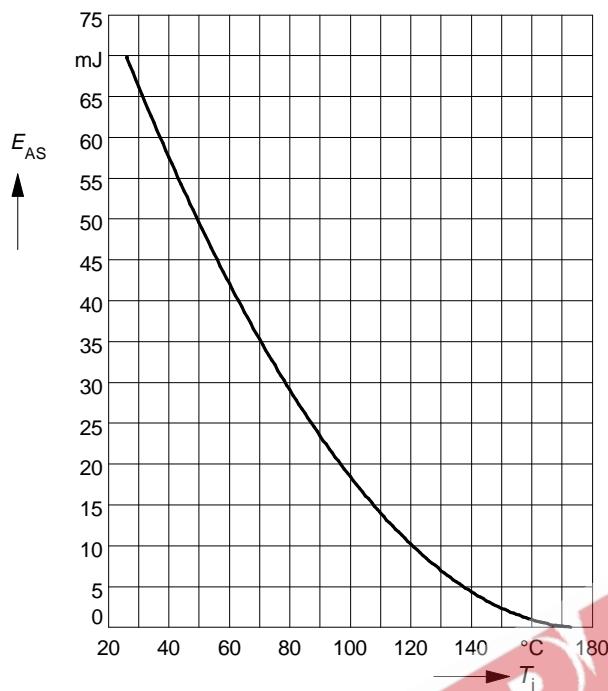


Forward characteristics of reverse diode

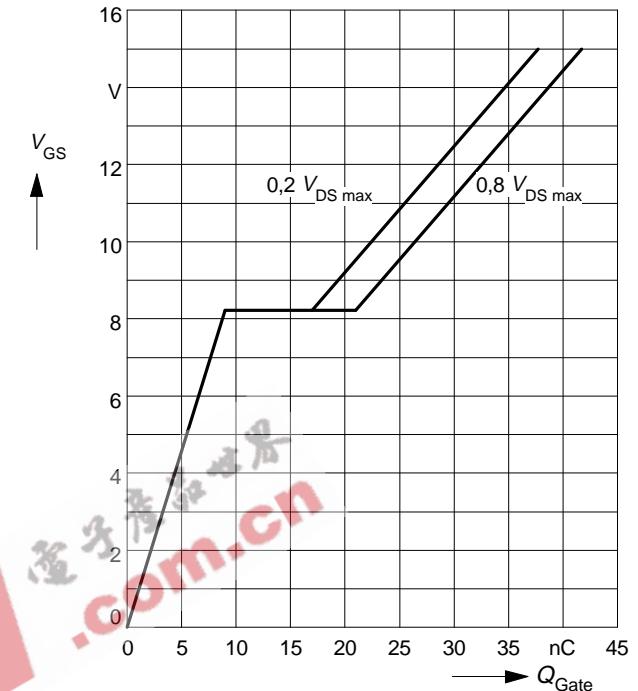
$I_F = f(V_{SD})$
parameter: T_j , $t_p = 80 \mu\text{s}$



Avalanche energy $E_{AS} = f(T_j)$
 parameter: $I_D = 29 \text{ A}$, $V_{DD} = 25 \text{ V}$
 $R_{GS} = 25 \Omega$, $L = 83 \mu\text{H}$

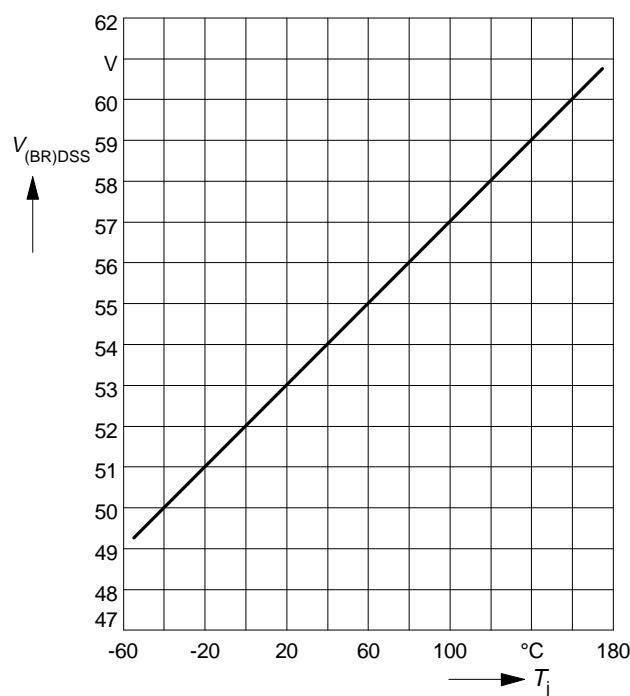


Typ. gate charge
 $V_{GS} = f(Q_{Gate})$
 parameter: $I_{D \text{ puls}} = 44 \text{ A}$



Drain-source breakdown voltage

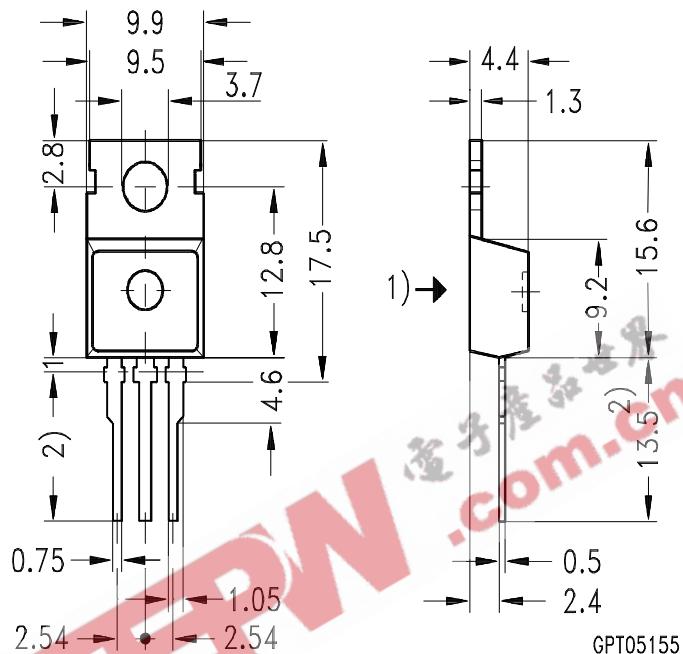
$$V_{(BR)DSS} = f(T_j)$$



Package Outlines

TO-220 AB

Dimension in mm



GPT05155

- 1) punch direction, burr max. 0.04
- 2) dip tinning
- 3) max. 14.5 by dip tinning press burr max. 0.05